

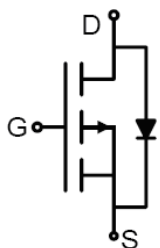

<p>Features</p> <ul style="list-style-type: none"> • $V_{DS} = -100V, I_D = -19A$ • $R_{DS(ON)} < 103m\Omega @ V_{GS} = -10V$ • $R_{DS(ON)} < 117m\Omega @ V_{GS} = -4.5V$ • High Power and current handling capability • Lead free product is acquired 	<p>Application</p> <ul style="list-style-type: none"> • Power Management Switches • Portable equipment and battery powered systems <p style="text-align: center; font-weight: bold; margin-top: 20px;">100%UIS TESTED! 100%ΔVds TESTED!</p>
 <p>Schematic Diagram</p>	 <p>TO-252(DPAK)top view</p>

Table 1. Absolute Maximum Ratings($T_A = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage($V_{GS} = 0V$)	-100	V
V_{GS}	Gate-Source Voltage($V_{DS} = 0V$)	± 20	V
I_D	Drain Current-Continuous($T_C = 25^\circ C$)	-19	A
	Drain Current-Continuous($T_C = 100^\circ C$)	-13.5	A
$I_{DM (pluse)}$	Drain Current-Continuous@ Current-Pulsed ^(Note1)	-76	A
P_D	Maximum Power Dissipation($T_C = 25^\circ C$)	79	W
	Maximum Power Dissipation($T_C = 100^\circ C$)	39.5	W
E_{AS}	Avalanche energy ^(Note2)	156	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55To175	$^\circ C$

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.9	$^\circ C/W$

Table 3. Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
B _{VDS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =-250μA	-100	-121		V
I _{BSS}	Zero Gate Voltage Drain Current	V _{DS} =-100V, V _{GS} =0V			-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1	-1.8	-2.5	V
g _{FS}	Forward Trans conductance	V _{DS} =-5V, I _D =-10A		26		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-10A		86	103	mΩ
		V _{GS} =-4.5V, I _D =-8A		90	117	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-25V, V _{GS} =0V, f=1.0MHz		3700		pF
C _{OSS}	Output Capacitance			90		pF
C _{rSS}	Reverse Transfer Capacitance			32		pF
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =-10V, V _{DS} =-50V, R _L =5Ω, R _{GEN} =9.1Ω		6		nS
t _r	Turn-on Rise Time			29		nS
t _{d(off)}	Turn-Off Delay Time			17		nS
t _f	Turn-Off Fall Time			24		nS
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-50V, I _D =-10A		72		nC
Q _{gs}	Gate-Source Charge			8.4		nC
Q _{gd}	Gate-Drain Charge			17.3		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				-19	A
V _{SD}	Forward on Voltage ^(Note3)	V _{GS} =0V, I _S =-10A			-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-15A, di/dt=100A/μs		32		ns
Q _{rr}	Reverse Recovery Charge	I _F =-15A, di/dt=100A/μs		53		nC

Notes1.RepetitiveRating:Pulsewidth limited by maximum junction temperature.

Notes2.EAScondition: T_J=25°C, V_{DD}=50V, V_G=-10V, R_g=25Ω, L=0.5mH.

Notes3.RepetitiveRating:Pulsewidthlimited by maximum junction temperature.

Typical Electrical And Thermal Characteristics(Curves)

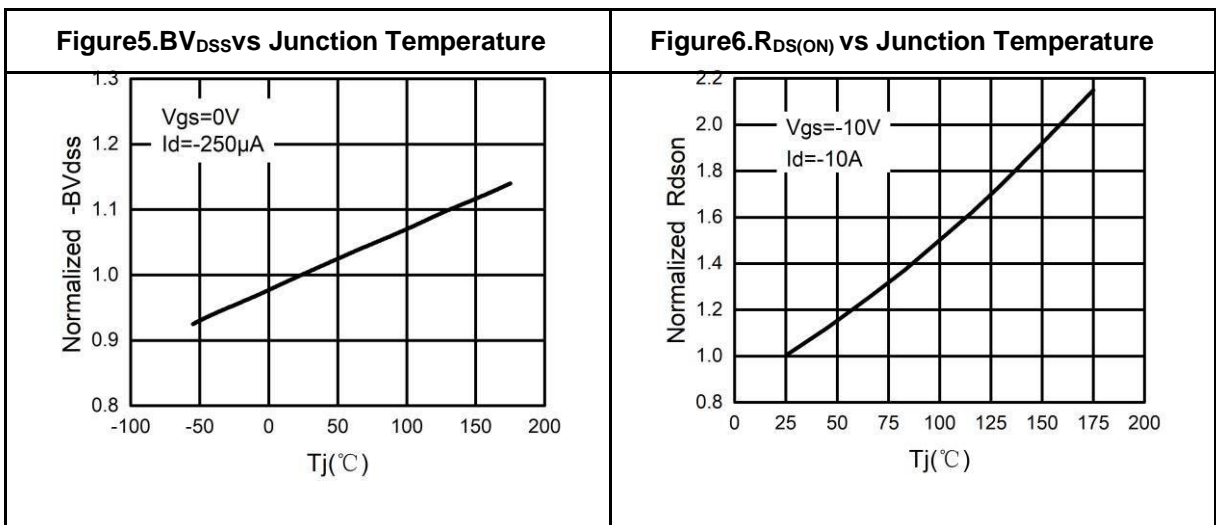
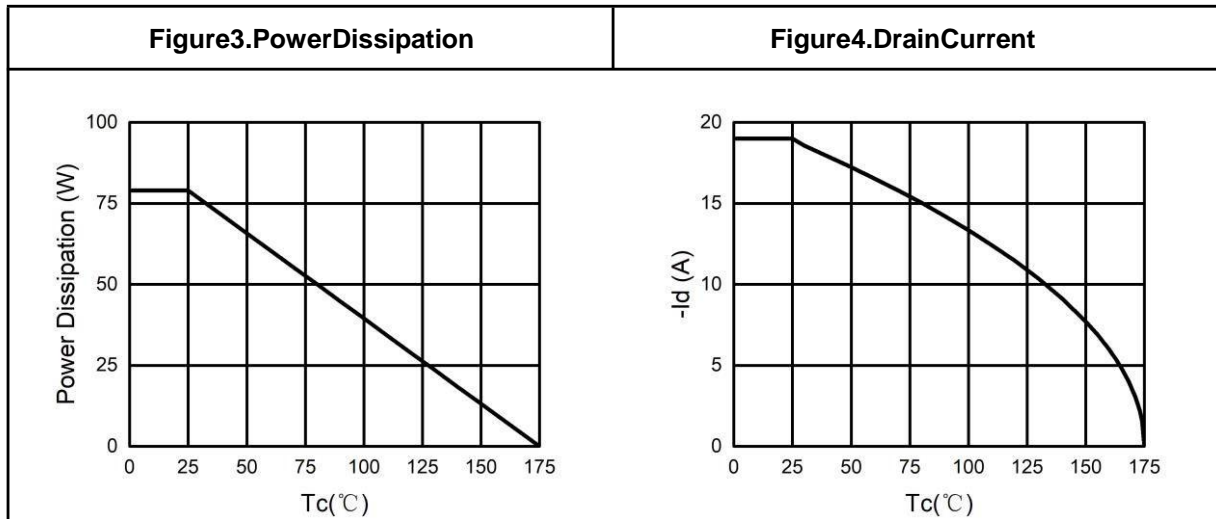
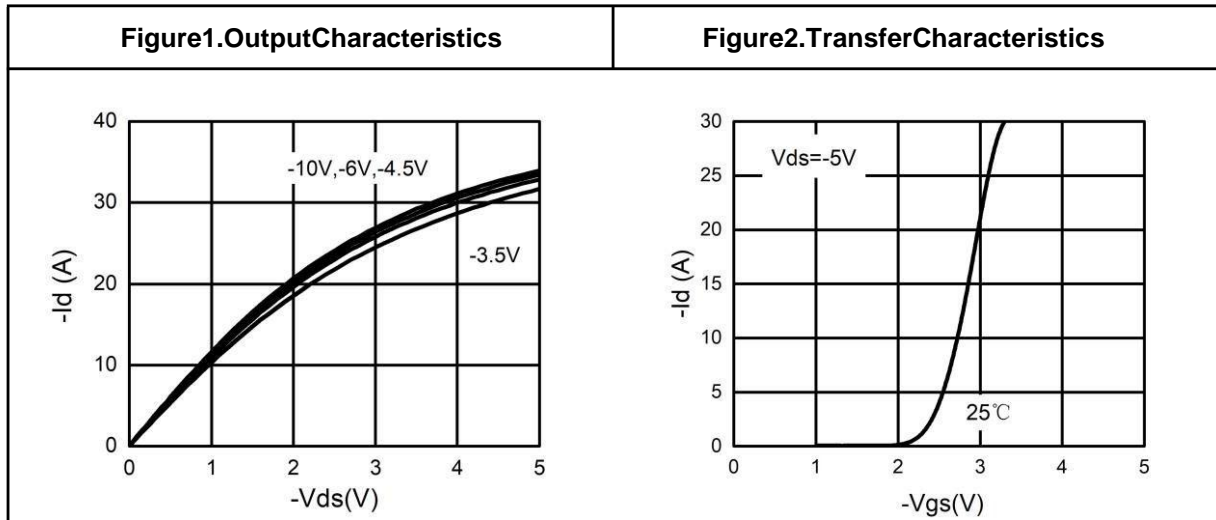


Figure7.GateChargeWaveforms

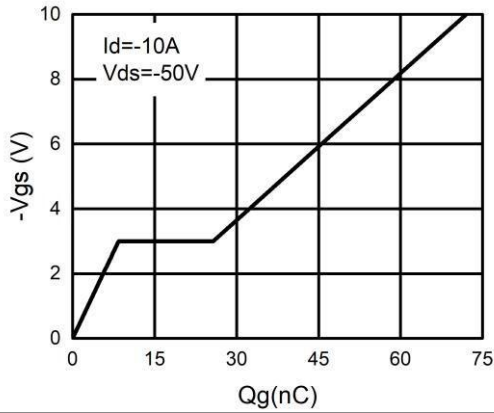


Figure8.Capacitance

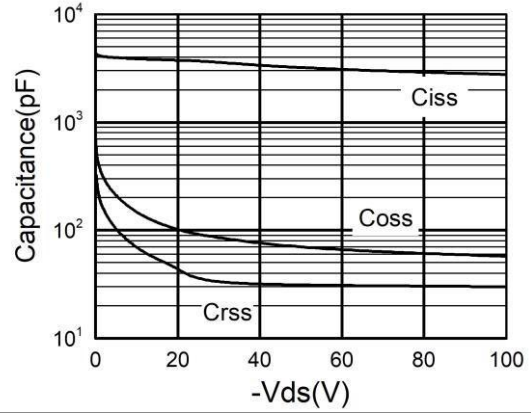


Figure9.Body-DiodeCharacteristics

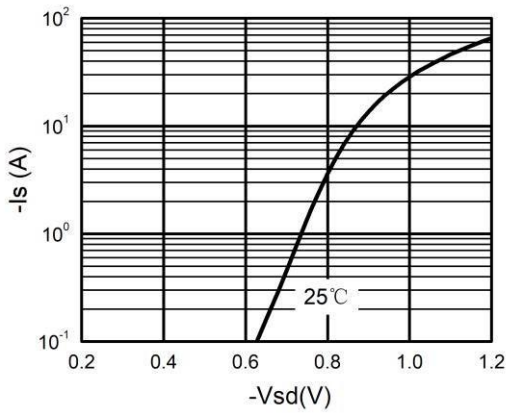
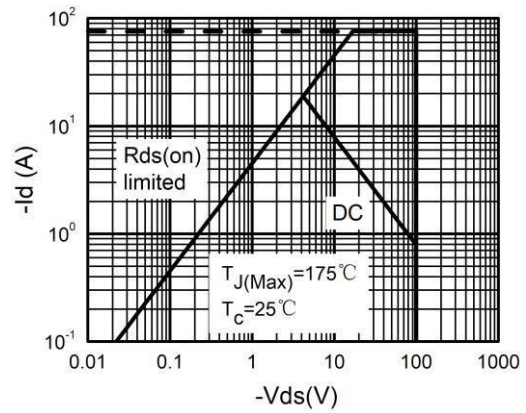
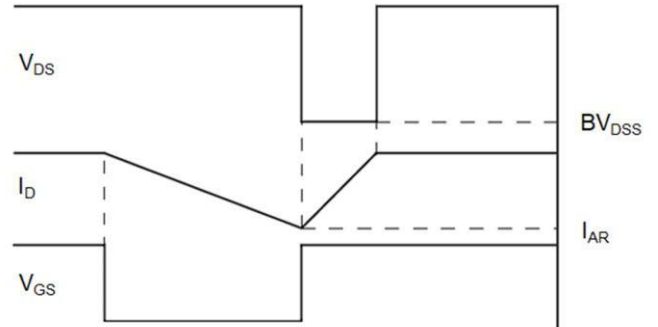
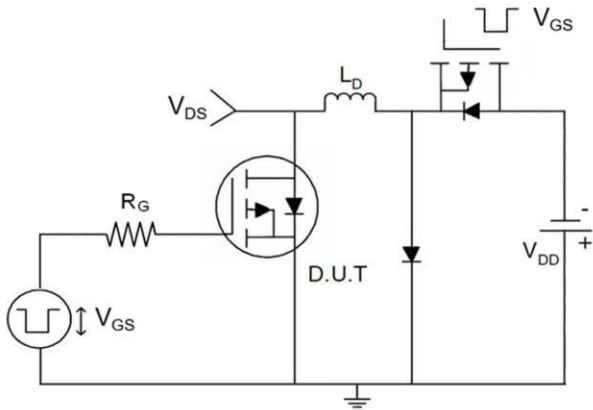


Figure10.MaximumSafeOperatingArea

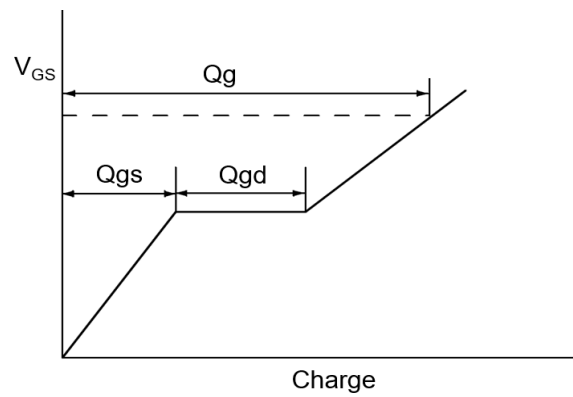
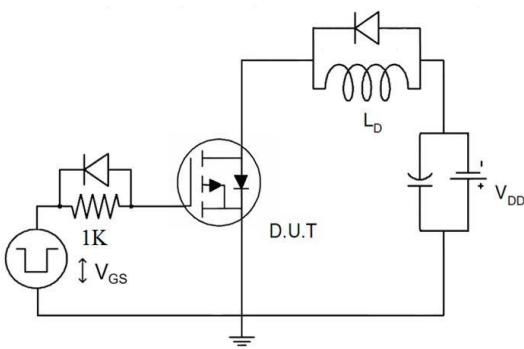


Test Circuit

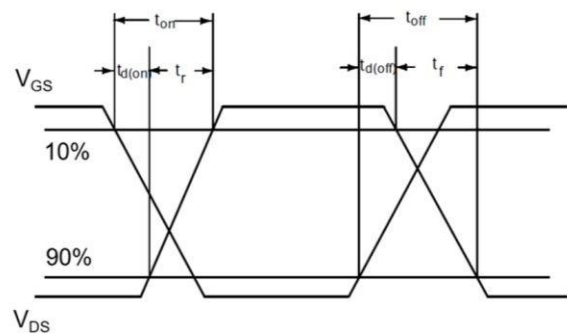
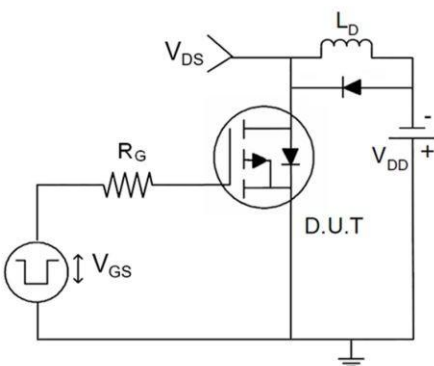
1) E_{AS} Test Circuits



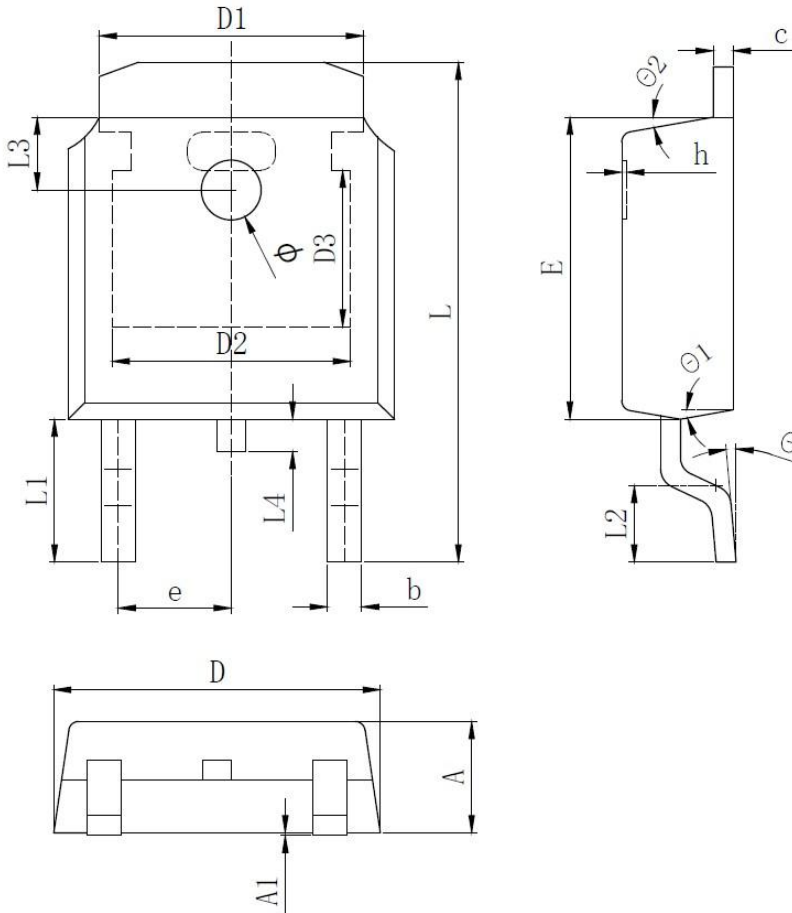
2) Gate Charge Test Circuit



3) Switch Time Test Circuit



TO-252 Package Information



SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
ϕ	1.100	1.200	1.300
θ	0°		8°
θ_1	9° TYP		
θ_2	9° TYP		